

2006

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Inventor: Low, Ranganathan, Fulcher
 Title: Bonding Pad For Low K Dielectric
 Filing date: 2003.06.20
 Express mail number: EV 327 363 863 US
 Attorney docket: 03-0187
 Customer number: 24,319

17522 U.S. PTO
 10/600255
 06/20/03

UTILITY PATENT APPLICATION TRANSMITTAL

Mail Stop Patent Application
 Commissioner for Patents
 P.O. Box 1450
 Alexandria VA 22313-1450

Sir:

Transmitted herewith for filing is the patent application described above. Enclosed are:

- ☒ Application cover sheet (1 sheet total).
☒ Specification (16 sheets total).
☒ Drawings (2 sheets total).
☒ Declaration and power of attorney (4 sheets total).
☒ Assignment with cover sheet (4 sheets total).
☐ Information disclosure statement and PTO-1449 (2 sheets total).
☐ Copies of IDS citations (# documents total).
☐ Check in the amount of \$#.
☒ Return receipt postcard with all items specifically itemized.

	# Filed	# Extra	Small Entity Rate	Fee	Large Entity Rate	Fee
Basic Fee			@ 375	\$	@ 750	\$750
Total Claims	20 - 20	= 0	@ \$9	\$	@ \$18	\$
Independent Claims	3 - 3	= 0	@ \$42	\$	@ \$84	\$
Multiple Dependent Claims		= 0	+\$140	\$	+ \$280	\$
Total				\$		\$750

The Commissioner is hereby authorized to charge payment of filing fees under 37 C.F.R. § 1.16 and processing fees under 37 C.F.R. § 1.17, and credit any overpayment to the LSI Logic Corporation deposit account number 12-2252.

Date

2003.06.20

Rick Barnes, 39,596